



## BAS40W /-04 /-05 /-06

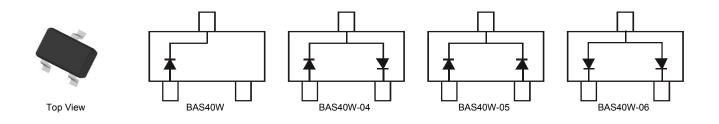
SURFACE MOUNT SCHOTTKY BARRIER DIODE

### Features

- Low Forward Voltage Drop
- Fast Switching
- Ultra-Small Surface Mount Package
- PN Junction Guard Ring for Transient and ESD Protection
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

## **Mechanical Data**

- Case: SOT323
- Case Material: Molded Plastic, "Green" Molding Compound, Note 4. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Solderable per MIL-STD-202, Method 208 3
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe).
- Polarity: See Diagrams Below
- Weight: 0.006 grams (approximate)



## Ordering Information (Notes 4 & 5)

Part Number	Case	Packaging
BAS40W-7-F	SOT323	3000/Tape & Reel
BAS40W-13-F	SOT323	10000/Tape & Reel
BAS40W-04-7-F	SOT323	3000/Tape & Reel
BAS40W-05-7-F	SOT323	3000/Tape & Reel
BAS40W-06-7-F	SOT323	3000/Tape & Reel

Notes: 1.

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

 See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

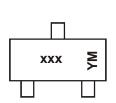
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. Product manufactured with Date Code 0627 (week 27, 2006) and newer are built with Green Molding Compound. Product manufactured prior to Date Code 0627 are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.

5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

## **Marking Information**

Data Codo Kov



xxx = Product Type Marking Code K43 = BAS40W K44 = BAS40W-04 K45 = BAS40W-05 K46 = BAS40W-06 YM = Date Code Marking Y = Year (ex: B = 2014) M = Month (ex: 9 = September)

Date Code Rey																
Year	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015	2016	2017	2018	2019	2020	2021
Code	Т	U	V	W	Х	Y	Z	А	В	С	D	E	F	G	Н	
-																
Month	Jan	F	eb	Mar	Apr	M	lay	Jun	Jul	A	ug	Sep	Oct	N	vo	Dec
Code	1		2	3	4		5	6	7		8	9	0	1	1	D



#### **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	40	V
RMS Reverse Voltage	V <sub>R(RMS)</sub>	28	V
Forward Continuous Current (Note 6)	I <sub>FM</sub>	200	mA
Non-Repetitive Peak Forward Surge Current @ t = 1.0s	I <sub>FSM</sub>	600	mA

## **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	PD	200	mW
Thermal Resistance Junction to Ambient Air (Note 6)	R <sub>0JA</sub>	625	°C/W
Operating Temperature Range	TJ	-55 to +125	°C
Storage Temperature Range	T <sub>STG</sub>	-65 to +150	°C

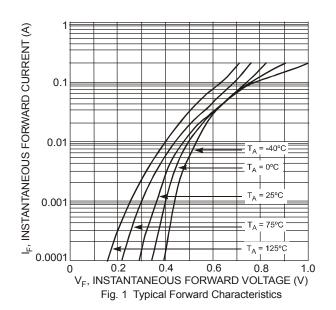
# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

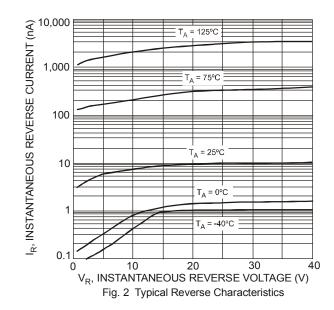
Characteristic	Symbol	Min	Мах	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	V <sub>(BR)R</sub>	40		V	I <sub>R</sub> = 10μA
Forward Voltage	V <sub>F</sub>	_	380 1000	mV mV	I <sub>F</sub> = 1.0mA, t <sub>p</sub> < 300μs I <sub>F</sub> = 40mA, t <sub>p</sub> < 300μs
Leakage Current (Note 7)	I <sub>R</sub>		200	nA	V <sub>R</sub> = 30V
Total Capacitance	CT	_	5.0	pF	V <sub>R</sub> = 0, f = 1.0MHz
Reverse Recovery Time	t <sub>rr</sub>	_	5.0	ns	$I_F = I_R = 10 \text{mA},$ $I_{rr} = 0.1 \text{ x } I_R, R_L = 100 \Omega$

Notes:

6. Device mounted on FR4 PC board with recommended pad layout, per http://www.diodes.com

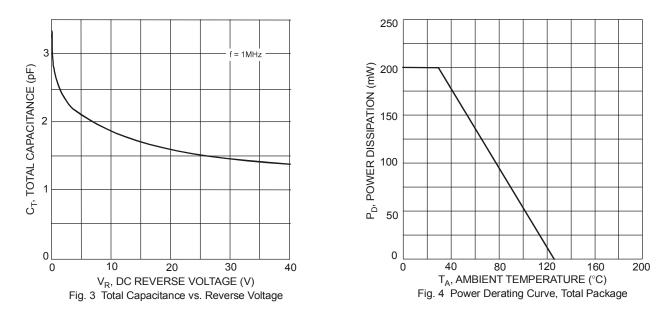
7. Short duration pulse test used to minimize self-heating effect.





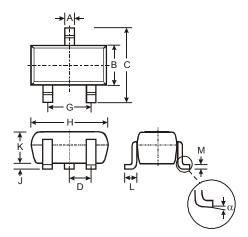


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# **Package Outline Dimensions**

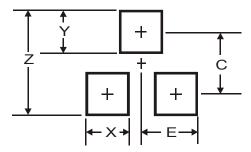
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SOT323							
Dim	Min	Max	Тур				
Α	0.25	0.40	0.30				
В	1.15	1.35	1.30				
С	2.00	2.20	2.10				
D	-	-	0.65				
G	1.20	1.40	1.30				
Н	1.80	2.20	2.15				
J	0.0	0.10	0.05				
Κ	0.90	1.00	1.00				
L	0.25	0.40	0.30				
М	0.10	0.18	0.11				
α	0°	8°	-				
All	All Dimensions in mm						

## Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	2.8
Х	0.7
Y	0.9
С	1.9
E	1.0



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